

## P-Ch 20V Fast Switching MOSFETs

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

## Product Summary



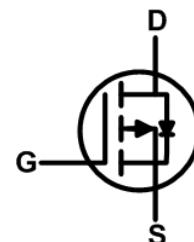
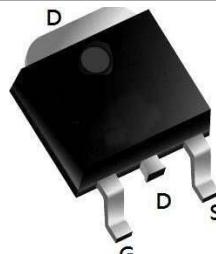
BVDSS	RDS(on)	ID
-20V	15mΩ	-30 A

## Description

The XR30P02 is the high cell density trenched P-ch MOSFETs, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications.

The XR30P02 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

## TO252-3L Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V^1$	-30	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V^1$	-19	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-120	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation <sup>3</sup>	3.9	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	---	45	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	50	°C/W

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Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise specified)

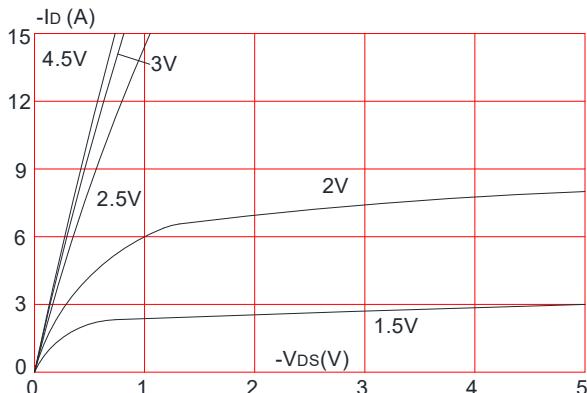
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-20	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=-12\text{V}$ , $V_{GS}=0\text{V}$ ,	-	-	-1	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 12\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=-250\mu\text{A}$	-0.4	-0.7	-1.0	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS}=-4.5\text{V}$ , $I_D=-8\text{A}$	-	15	25	$\text{m}\Omega$
		$V_{GS}=-2.5\text{V}$ , $I_D=-6\text{A}$	-	22	30	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=-6\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	1300	-	pF
$C_{oss}$	Output Capacitance		-	302	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	279	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=-6\text{V}$ , $I_D=-8\text{A}$ , $V_{GS}=-4.5\text{V}$	-	19	-	nC
$Q_{gs}$	Gate-Source Charge		-	4	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	5	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=-6\text{V}$ , $I_D=-5\text{A}$ , $V_{GS}=-4.5\text{V}$ , $R_{\text{GEN}}=2.5\Omega$	-	11	-	ns
$t_r$	Turn-on Rise Time		-	36	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	29	-	ns
$t_f$	Turn-off Fall Time		-	8	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	-30	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-120	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=-8\text{A}$	-	-0.8	-1.2	V

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

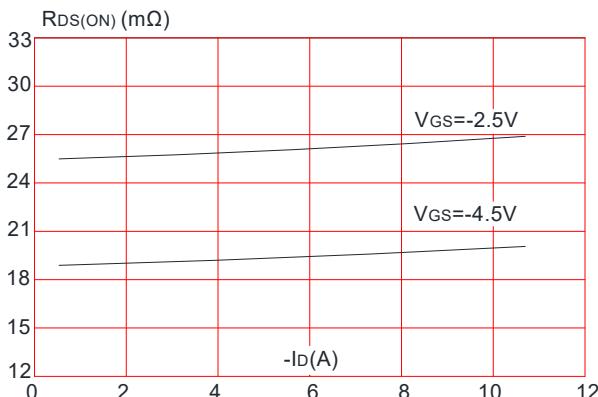
2. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$

## Typical Performance Characteristics

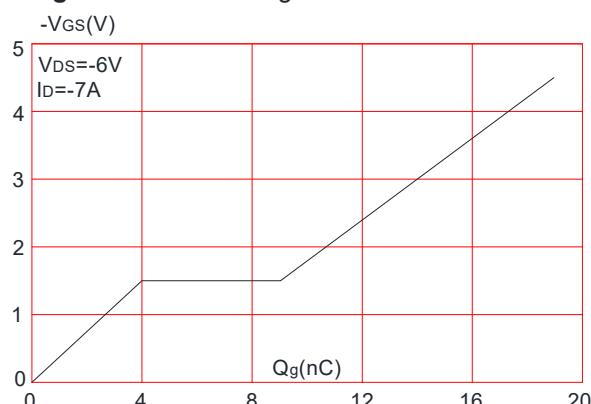
**Figure 1:** Output Characteristics



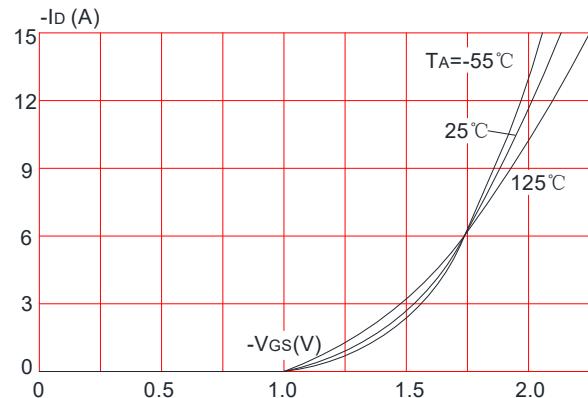
**Figure 3:** On-resistance vs. Drain Current



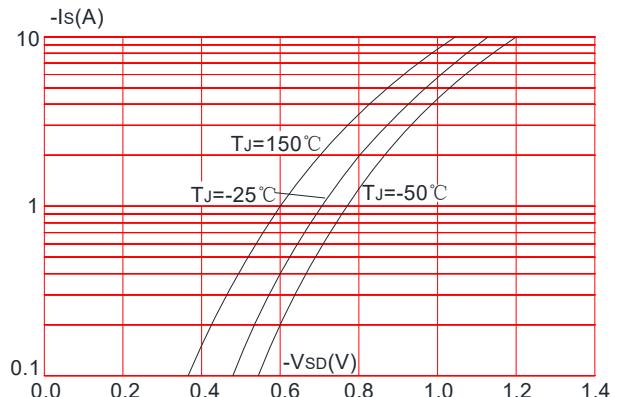
**Figure 5: Gate Charge Characteristics**



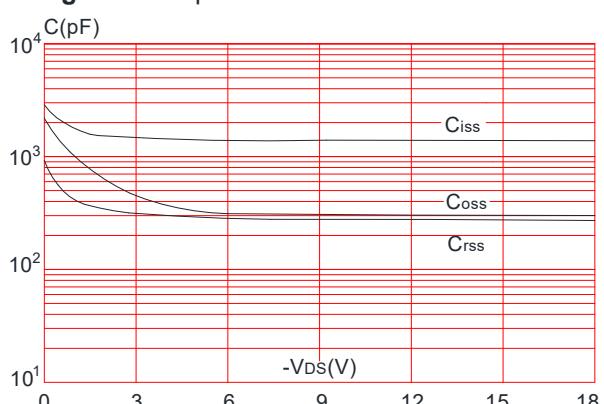
**Figure 2:** Typical Transfer Characteristics

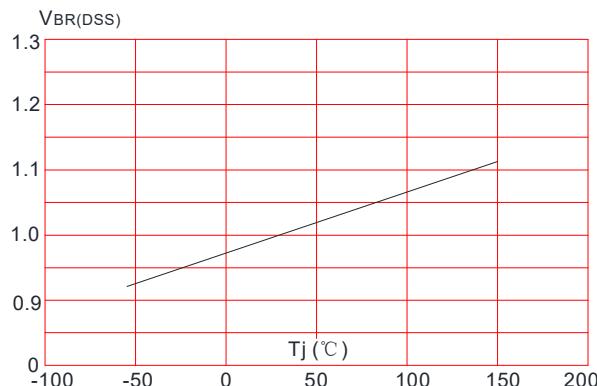
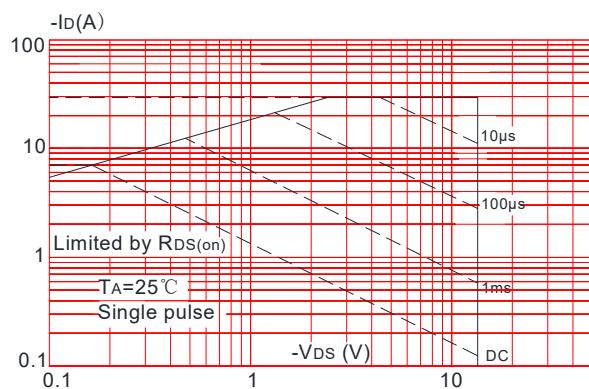
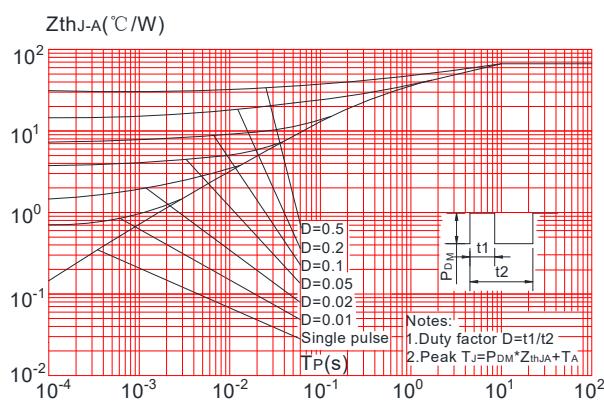
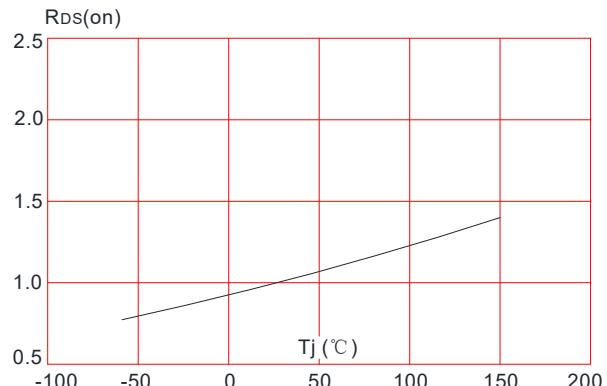


**Figure 4:** Body Diode Characteristics



**Figure 6: Capacitance Characteristics**



**P-Ch 20V Fast Switching MOSFETs****Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature**Figure 9:** Maximum Safe Operating Area**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient**Figure 8:** Normalized on Resistance vs. Junction Temperature**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature